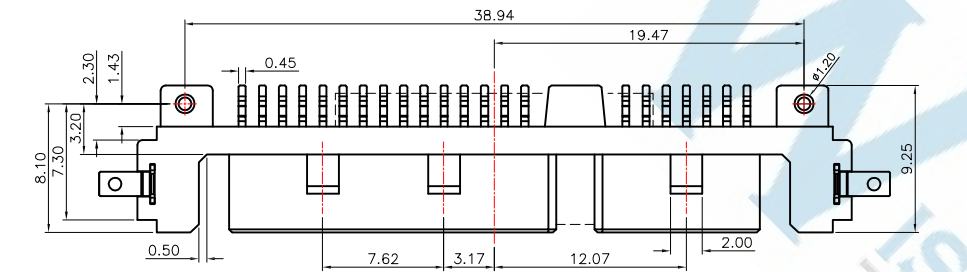
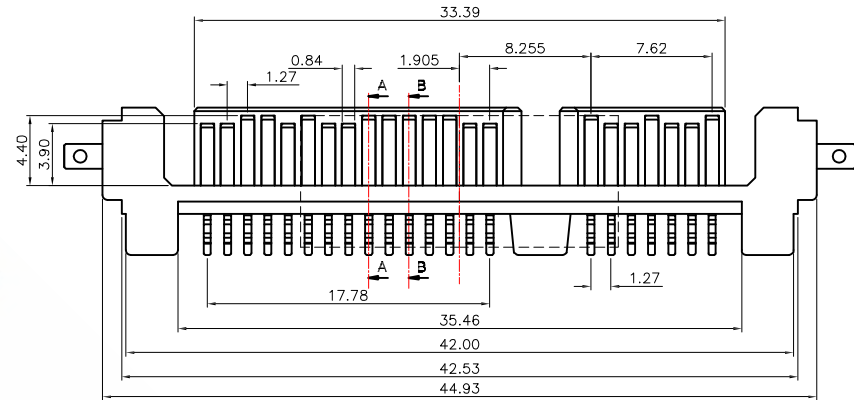
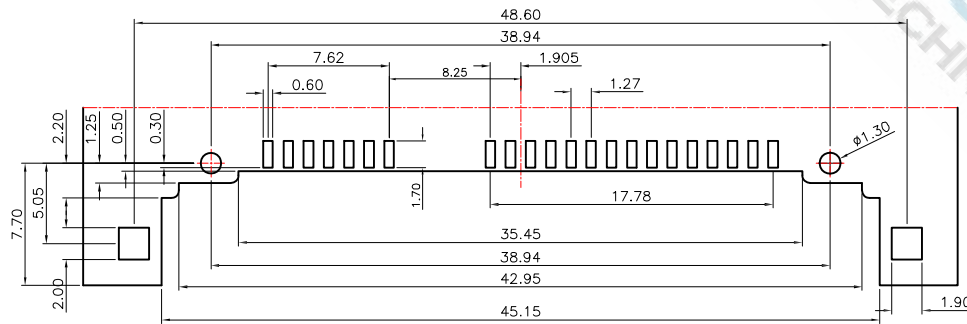


SECTION A-A SECTION B-B



NOTE:

1. MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0
 - COVER: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0
 - TERMINAL: COPPER ALLOY, THICKNESS = 0.25 mm
 - FOR LOCK: COPPER ALLOY, THICKNESS = 0.30 mm
2. PLATING:
 - CONTACT: GOLD OVER 50u" MIN NICKEL UNDERPLATE
 - SOLDER TAIL: 75u" MIN TIN 50u" MIN NICKEL UNDERPLATE
 - GOLD SPECIFICATION: SEE TABLE,
3. ELECTRICAL SPECIFICATION:
 - CURRENT RATING: 1.5 AMPERE PER CONTACT
 - CONTACT RESISTANCE: 30 MILLIOHMS MAX.
 - INSULATION RESISTANCE: 1000 MEGOHMS MIN.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500 VDC.
 - OPERATING TEMPERATURE: -20°C ~ +85°C



RECOMMENDED P.C. B LAYOUT
THICKNESS=1.0mm

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審核(CH'K)	Calvin	圖名(NAME) SATA 22P 公頭沉板式		WISCONN Technology Co., Ltd Tel: 02-2742-1798 Fax: 02-2742-1898									
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena												
	料號(PART NUMBER)	WSTAM-2215LBSSR		圖號(DRAW NUMBER)	T006		比例(SCALE)	1/1					圖紙(SIZE)	A4	頁次(SHEET)	1	版次(REV.)	A
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期(DATE)	OCT.15.2007	圖檔(FILE NAME .DWG)											